

Time-Lag SMD Fuses 1206

multicomp PRO

**RoHS
Compliant**



Description

The SMD fuses stand out due to their ultra-small size and excellent electrical performance, reliability and quality. The solder-free design provides outstanding on-off and temperature cycling characteristics during operation and also makes our chip fuses more heat and shock tolerant than typical subminiature fuses.

Applications

Industrial products such as cellphones, DVD players, battery packs, hard disk drives and digital cameras.

Features

- High inrush current withstanding capability
- Compatible with reflow and wave soldering
- Ceramic and glass construction
- Excellent environmental integrity
- AEC-Q200 Automotive Grade Certified
- Lead-free and Halogen-free
- Designed to UL 248-14

Specifications

Operating Temperature	: -55°C to +150°C
Storage Conditions	: +10°C to +60°C
Relative Humidity	: ≤ 75% yearly average without dew, maximum 30 days at 95%
Vibration Resistance	: 24 cycles at 15 min. each 10-60Hz at 0.75mm amplitude 60-2000Hz at 10g acceleration

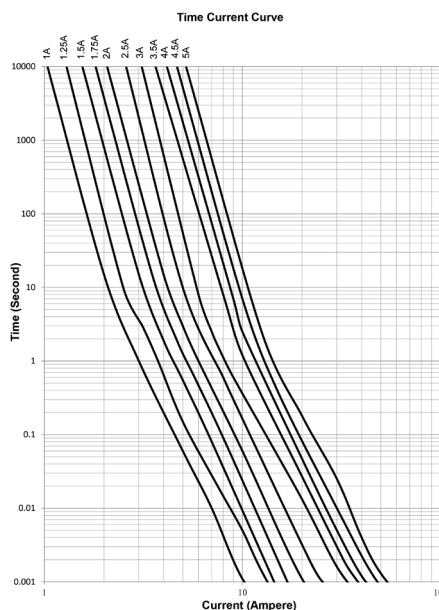
Electrical Characteristics

Time vs Current Characteristics Table

(measured with constant current power supply)

Time vs Current Characteristics				
Rated current	100%	250%	300%	1000%
1A to 5A	>4h	<5s	0.1s~3s	0.2ms~20ms

Average Time Current (I-T) Curves



Newark.com/multicomp-pro
Farnell.com/multicomp-pro
sg.element14.com/b/multicomp-pro

multicomp PRO

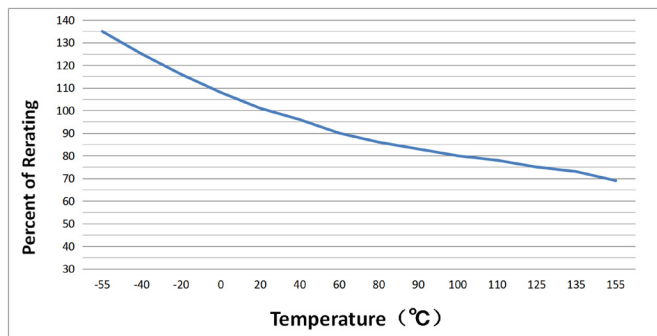
Time-Lag SMD Fuses 1206

Electrical Characteristics at 25°C

Amp Code	Rated Current	Rated Voltage DC	Typical Voltage Drop (mV)	Breaking Capacity	Typical Melting I ² T (A ² s)	Typical Cold Resistance (mΩ)	Alpha Mark
1100	1A	12VAC 63VDC	530	50A @ 12V AC 50A @ 63V DC	0.15	465	H
1150	1.5A		468		0.21	215	K
1200	2A		320		0.43	130	N
1250	2.5A		250		0.72	75	O
1300	3A		197		1.75	48	P
1400	4A		175		2.65	33	S
1500	5A	32V DC 12V AC	150	100A @ 32V DC 100A @ 12V AC	4.15	23	T

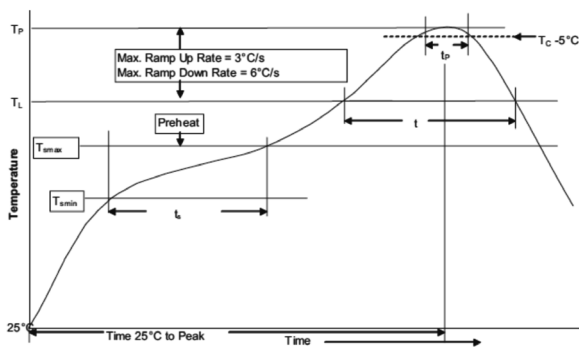
1. DC Interrupting Rating (Measured at rated voltage, time constant of less than 50 microseconds, battery source)
2. DC Cold Resistance are measured at <10% of rated current in ambient temperature of 25°C
3. Typical Pre-arcing I²t are measured at 10In Current

Temperature Re-rating Curve



Normal ambient temperature : 23 ±3°C
 Operating temperature : -55°C ~ +150°C, with proper correction factor applied

Soldering Parameters

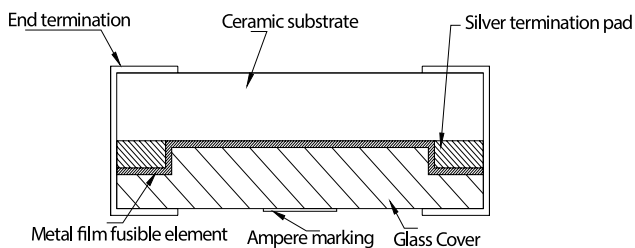


1. Infrared Reflow:
 Temperature: 260°C
 Time: 5S
 Recommend reflow profile
2. Wave Soldering:
 Reservoir Temperature: 260°C
 Time in Reservoir: 10sec Max.

Time-Lag SMD Fuses 1206

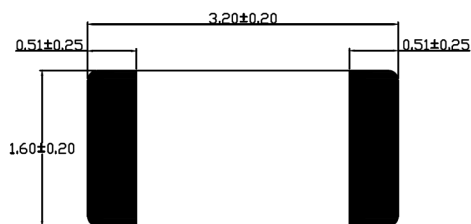
Profile Feature		Pb-Free Assembly
Average Ramp-UP Rate(Tsmax to Tp)		3°C/s Max.
Preheat	Temperature Min (Ts min)	150°C
	Temperature Max (Ts max)	200°C
	Time (Tsm in to Ts max)	60sec to 120sec
Liquidous temperature(TL)		217°C
Time at liquidous(tL)		60 to 150S
Peak package body temperature (Tp)		260°C
Time (tp) within 5°C of the specified classification temperature (Tc)		30S
Average ramp-down rate (Tp to Tsmax)		6°C/s Max.
Time (25°C to Peak Temperature)		8 Minutes Max.

Mechanical Specifications

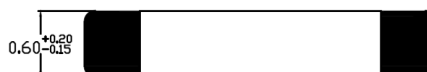


Diagram

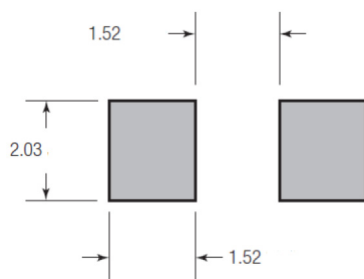
Top view



Side view



Recommended Land Pattern

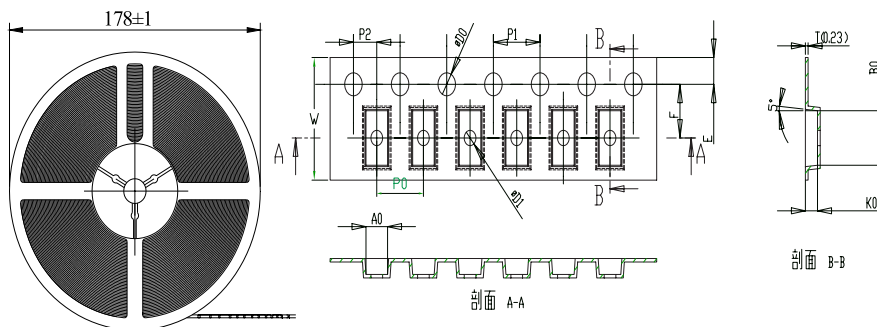


Dimensions : Millimetres

Time-Lag SMD Fuses 1206

multicomp PRO

Packing Information



W	E	F	D0	D1	P0	P1	P2	P0×10	t	A0	B0	K0
8 ±0.2	1.75 ±0.1	3.5 ±0.05	1.5 +0.1/-0	1 ±0.1	4 ±0.05	4 ±0.01	2 ±0.05	40 ±0.2	0.25 ±0.05	1.85 ±0.1	3.56 ±0.1	1.04 ±0.1

Part Number Table

Description	Part Number
SMD Fuse, Time-Lag, 1A, 63V DC, 1206	MP001606
SMD Fuse, Time-Lag, 1.5A, 63V DC, 1206	MCCFB1206TTT/1.5
SMD Fuse, Time-Lag, 2A, 63V DC, 1206	MP001607
SMD Fuse, Time-Lag, 2.5A, 63V DC, 1206	MCCFB1206TTT/2.5
SMD Fuse, Time-Lag, 3A, 63V DC, 1206	MP001608
SMD Fuse, Time-Lag, 3A, 63V DC, 1206	MCCFB1206TTT/3
SMD Fuse, Time -Lag, 3A, 72V DC / 63V DC, 1206	MP006275
SMD Fuse, Time-Lag, 4A, 32V DC, 1206	MCCFB1206TTT/4
SMD Fuse, Time-Lag, 4A, 63V DC, 1206	MP001609
SMD Fuse, Time-Lag, 5A, 32V DC, 1206	MCCFB1206TTT/5
SMD Fuse, Time-Lag, 5A, 32V DC, 1206	MP001610

Dimensions : Millimetres

Important Notice : This data sheet and its contents (the "Information") belong to the members of the AVNET group of companies (the "Group") or are licensed to it. No licence is granted for the use of it other than for information purposes in connection with the products to which it relates. No licence of any intellectual property rights is granted. The Information is subject to change without notice and replaces all data sheets previously supplied. The Information supplied is believed to be accurate but the Group assumes no responsibility for its accuracy or completeness, any error in or omission from it or for any use made of it. Users of this data sheet should check for themselves the Information and the suitability of the products for their purpose and not make any assumptions based on information included or omitted. Liability for loss or damage resulting from any reliance on the Information or use of it (including liability resulting from negligence or where the Group was aware of the possibility of such loss or damage arising) is excluded. This will not operate to limit or restrict the Group's liability for death or personal injury resulting from its negligence. Multicomp Pro is the registered trademark of Premier Farnell Limited 2019.

Newark.com/multicomp-pro
Farnell.com/multicomp-pro
sg.element14.com/b/multicomp-pro

multicomp PRO